

# STARPOWER

SEMICONDUCTOR

# IGBT

## GD300SGL120C2S

Molding Type Module

1200V/300A 1 in one-package

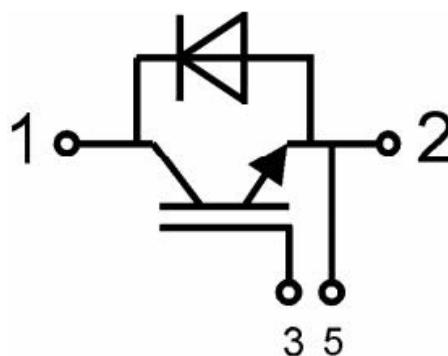


### General Description

STARPOWER IGBT Power Module provides ultra Low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

### Features

- High short circuit capability, self limiting to  $6 \cdot I_C$
- 10 $\mu$ s short circuit capability
- $V_{CE(sat)}$  with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology



Equivalent Circuit Schematic

### Typical Applications

- AC inverter drives
- Switching mode power supplies
- Electronic welders at  $f_{sw}$  up to 20kHz

### Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Description	GD300SGL120C2S	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V

Symbol	Description	GD300SGL120C2S	Units
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_C=25^\circ\text{C}$ @ $T_C=100^\circ\text{C}$	600	A
		300	
$I_{CM(1)}$	Pulsed Collector Current	600	A
$I_F$	Diode Continuous Forward Current	300	A
$I_{FM}$	Diode Maximum Forward Current	600	A
$P_D$	Maximum power Dissipation @ $T_j=175^\circ\text{C}$	3000	W
$T_{SC}$	Short Circuit Withstand Time @ $T_j=125^\circ\text{C}$	10	$\mu\text{s}$
$T_{jmax}$	Maximum Junction Temperature	175	$^\circ\text{C}$
$T_j$	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
$I^2t$ -value, Diode	$V_R=0\text{V}$ , $t=10\text{ms}$ , $T_j=125^\circ\text{C}$	19000	$\text{A}^2\text{s}$
$V_{ISO}$	Isolation Voltage RMS, $f=50\text{Hz}$ , $t=1\text{min}$	2500	V
Mounting Torque	Signal Terminal Screw:M4	1.1 to 2.0	N.m
	Power Terminal Screw:M6	2.5 to 5.0	
	Mounting Screw:M6	3 to 6	N.m

**Notes:**

(1) Repetitive rating: Pulse width limited by max. junction temperature

**Electrical Characteristics of IGBT**  $T_C=25^\circ\text{C}$  unless otherwise noted**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$T_j=25^\circ\text{C}$	1200			V
$I_{CES}$	Collector Cut-Off Current	$V_{CE}=V_{CES}$ , $V_{GE}=0\text{V}$ , $T_j=25^\circ\text{C}$			5.0	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}$ , $V_{CE}=0\text{V}$ , $T_j=25^\circ\text{C}$			400	nA

**On Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=12\text{mA}$ , $V_{CE}=V_{GE}$ , $T_j=25^\circ\text{C}$	5	6.2	7.0	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=300\text{A}$ , $V_{GE}=15\text{V}$ , $T_j=25^\circ\text{C}$		1.9		V
		$I_C=300\text{A}$ , $V_{GE}=15\text{V}$ , $T_j=125^\circ\text{C}$		2.1		

**Switching Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}$ , $I_C=300\text{A}$ ,		90		ns

$t_r$	Rise Time	$R_G=4.7\Omega, V_{GE} = \pm 15V,$		55		ns
$t_{d(off)}$	Turn-Off Delay Time	$T_j=25^\circ C$		460		ns
$t_f$	Fall Time			55		ns
$E_{on}$	Turn-On Switching Loss	$V_{CC}=600V, I_C=300A,$ $R_G=4.7\Omega, V_{GE} = \pm 15V,$		28		mJ
$E_{off}$	Turn-Off Switching Loss	$T_j=25^\circ C$		25		mJ
$t_{d(on)}$	Turn-On Delay Time			110		ns
$t_r$	Rise Time			60		ns
$t_{d(off)}$	Turn-Off Delay Time			500		ns
$t_f$	Fall Time	$V_{CC}=600V, I_C=300A,$ $R_G=4.7\Omega, V_{GE} = \pm 15V,$		60		ns
$E_{on}$	Turn-On Switching Loss	$T_j=125^\circ C$		31		mJ
$E_{off}$	Turn-Off Switching Loss			27		mJ
$C_{ies}$	Input Capacitance			21		nF
$C_{oes}$	Output Capacitance	$V_{CE} = 25V, f=1MHz,$		1.5		nF
$C_{res}$	Reverse Transfer Capacitance	$V_{GE} = 0V$		0.9		nF
$I_{SC}$	SC Data	$t_{sc} \leq 10\mu s, V_{GE}=15V,$ $T_j=125^\circ C, V_{CC}=900V,$ $V_{CEM} \leq 1200V$		1300		A
$L_{CE}$	Stray inductance				20	nH
$R_{CC'+EE'}$	Module lead resistance, terminal to chip	$T_C=25^\circ C$		0.18		m $\Omega$

### Electrical Characteristics of DIODE $T_C=25^\circ C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units	
$V_F$	Diode Forward Voltage	$I_F=300A$	$T_j=25^\circ C$		2.0	2.4	V
			$T_j=125^\circ C$		2.2	2.5	
$Q_r$	Diode Reverse Recovery Charge	$I_F=300A,$	$T_j=25^\circ C$		27		$\mu C$
			$T_j=125^\circ C$		50		
$I_{RM}$	Diode Peak Reverse Recovery Current	$V_R=600V,$ $di/dt=-2400A/\mu s,$ $V_{GE}=-15V$	$T_j=25^\circ C$		120		A
			$T_j=125^\circ C$		170		
$E_{rec}$	Reverse Recovery Energy		$T_j=25^\circ C$		9		mJ
			$T_j=125^\circ C$		20		

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (IGBT Part, per Module)		0.06	K/W
$R_{\theta JC}$	Junction-to-Case (DIODE Part, per Module)		0.12	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.035		K/W
Weight	Weight of Module	310		g

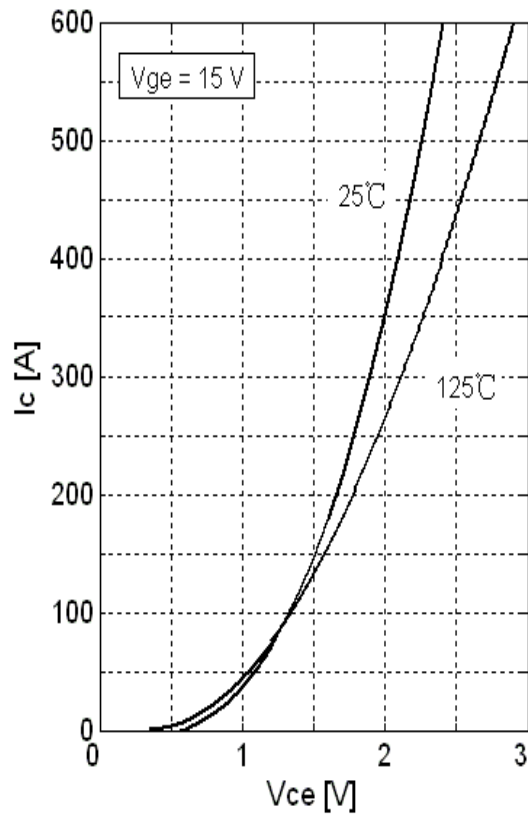


Fig 1. Typical Output Characteristics

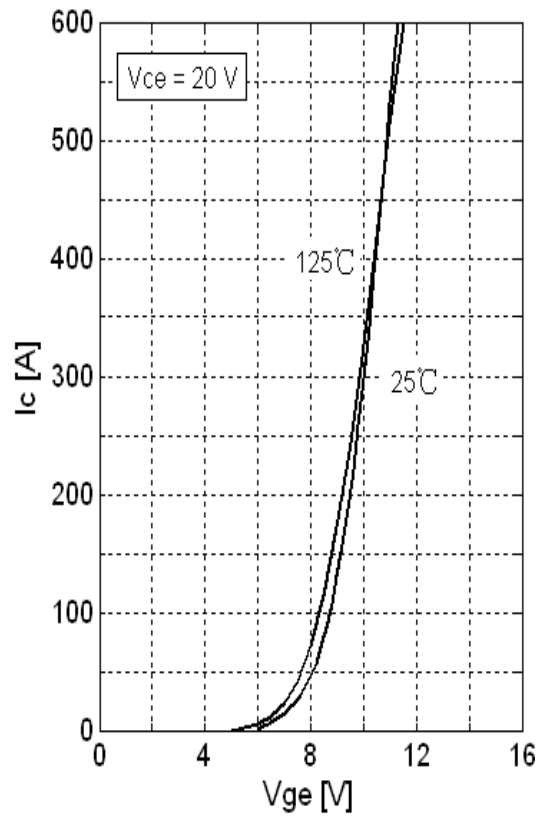


Fig 2. Typical Transfer Characteristics

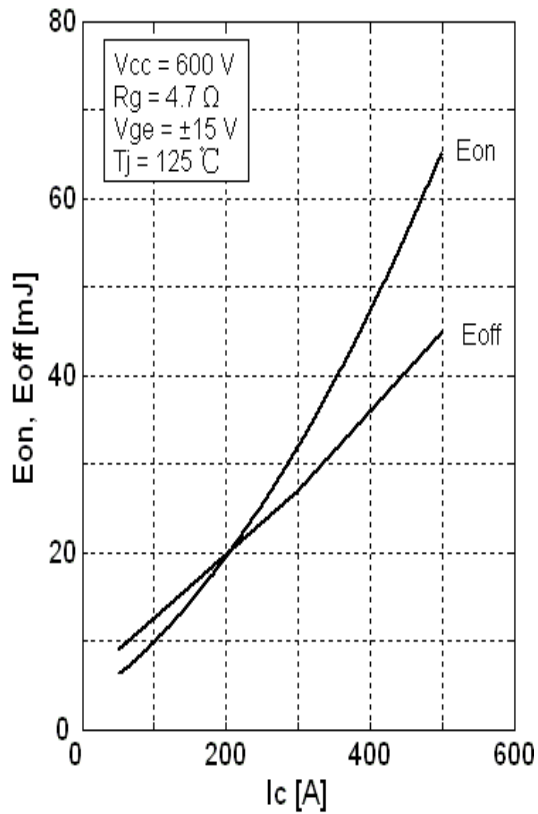


Fig 3. Switching Loss vs Collector Current

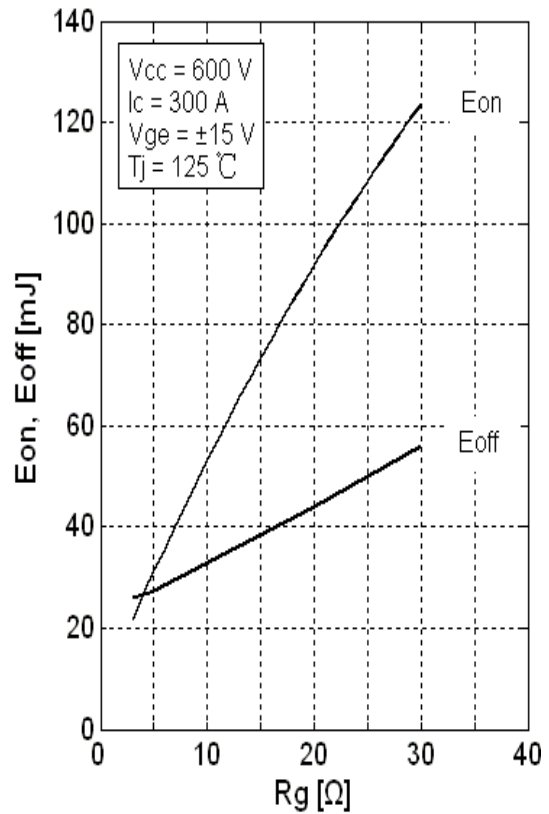


Fig 4. Switching Loss vs Gate Resistor

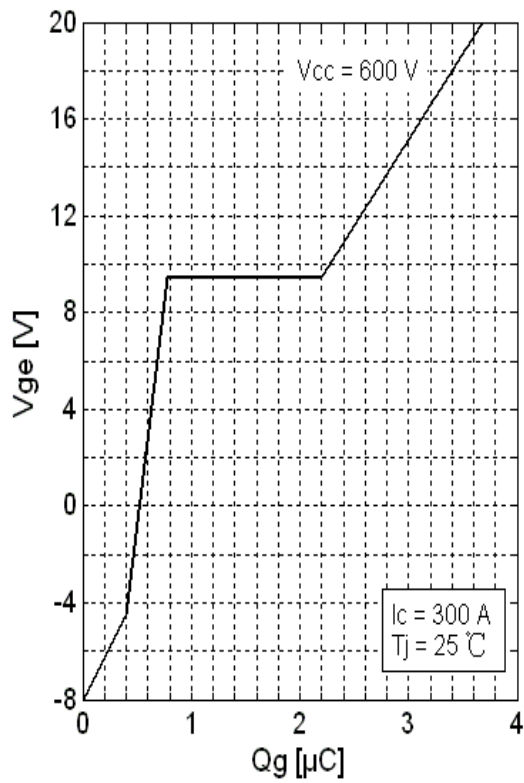


Fig 5. Gate Charge Characteristics.

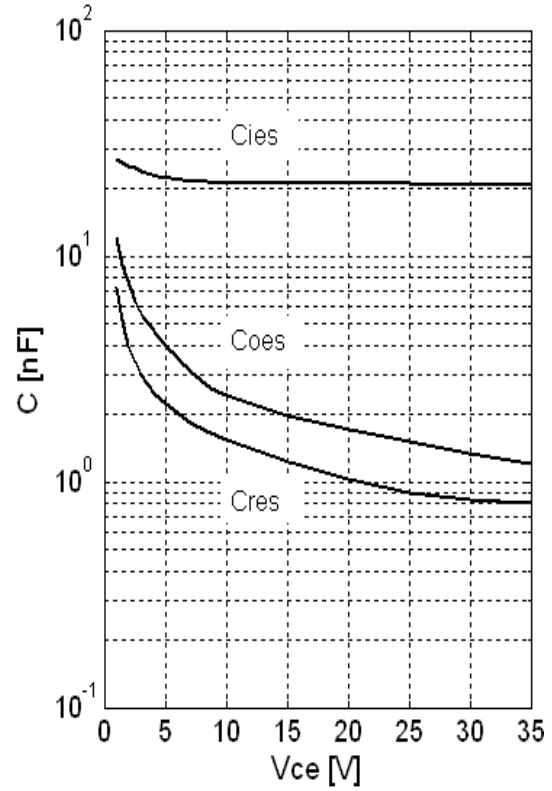


Fig 6. Typical Capacitance vs Collector-Emitter Voltage

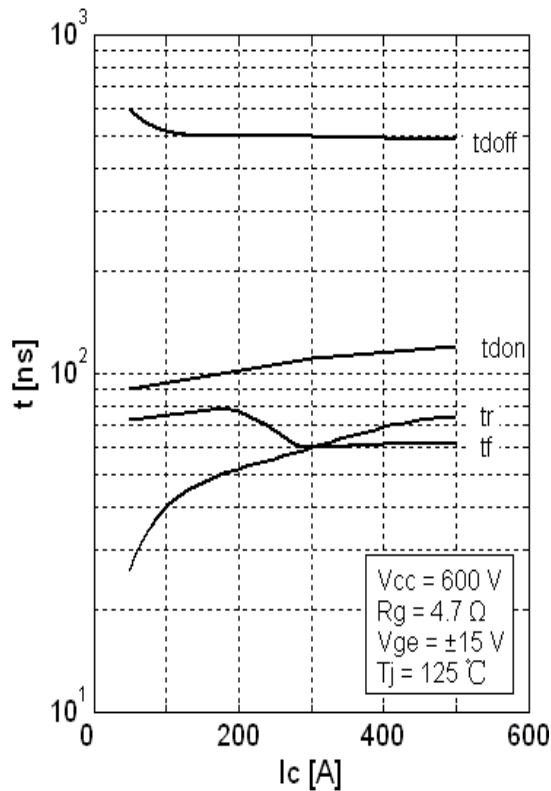


Fig 7. Typical Switching Times vs  $I_c$

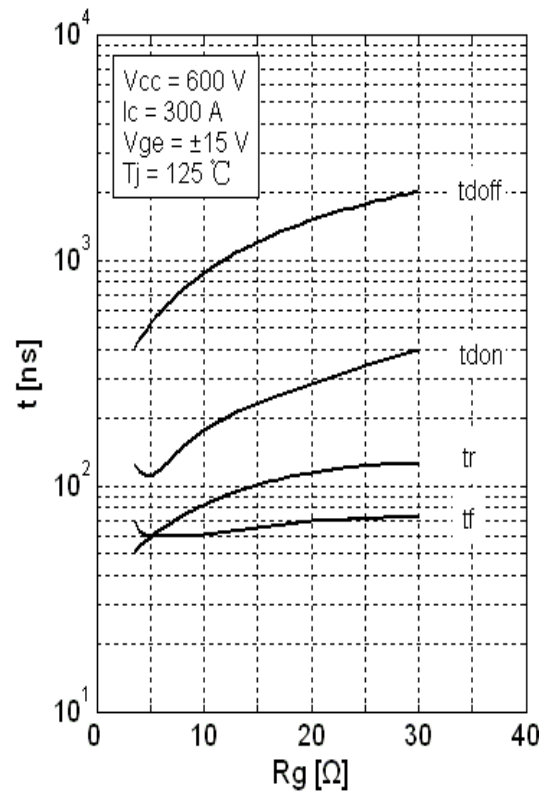


Fig 8. Typical Switching Times vs Gate Resistance  $R_G$

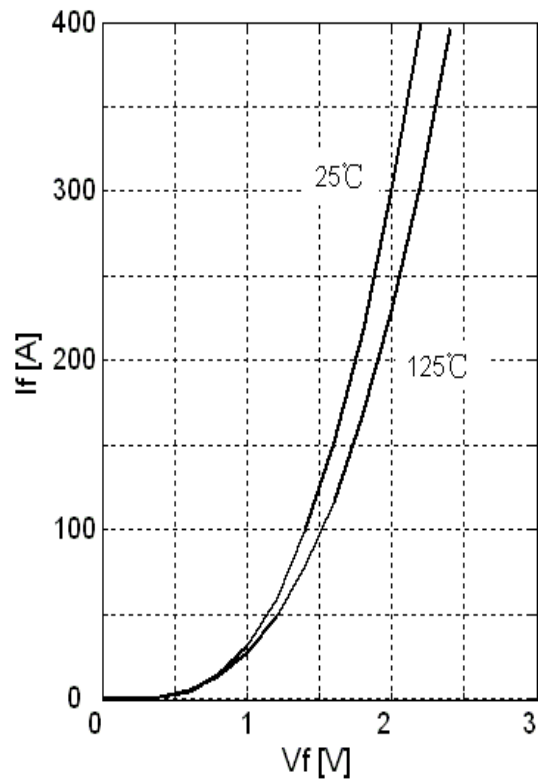


Fig 9. Typical Forward Characteristics (diode)

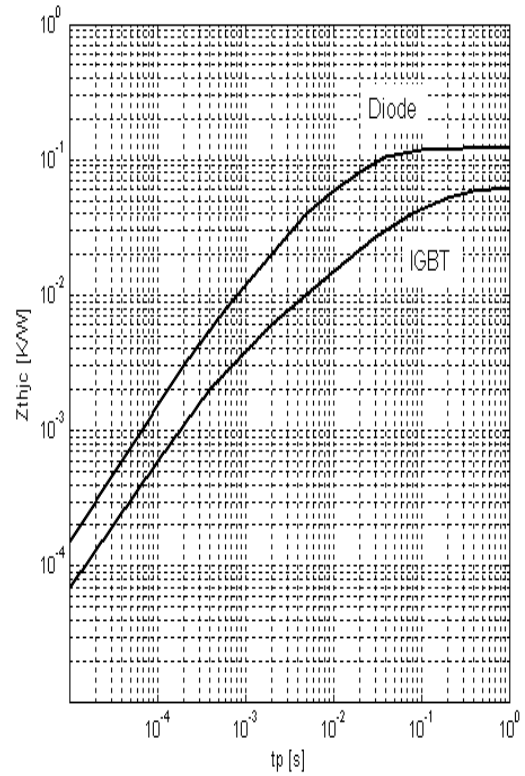
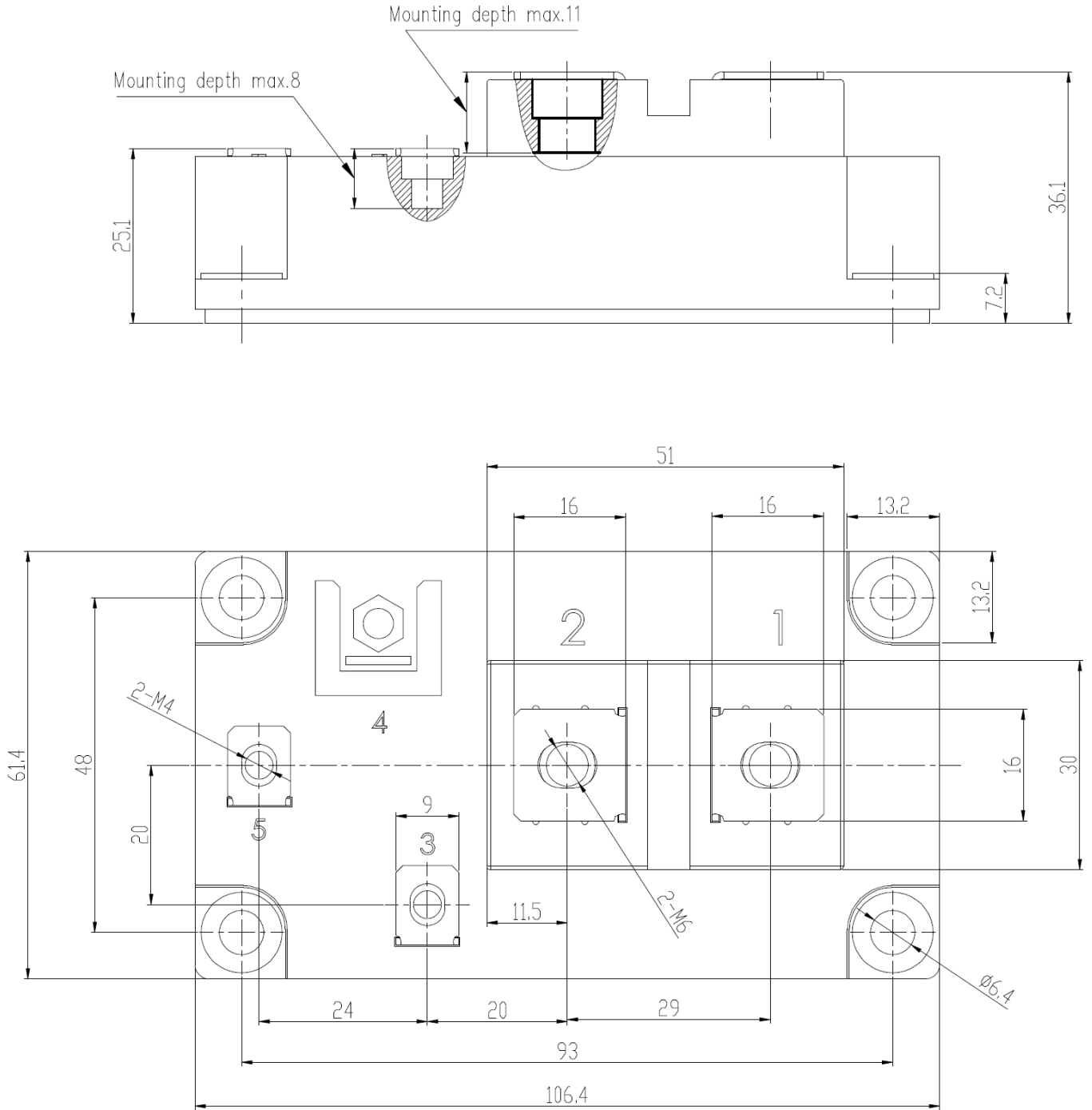


Fig 10. Transient thermal impedance

Package Dimension

Dimensions in Millimeters





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